

Title (en)

LAYERED STRUCTURES AND METHOD FOR PRODUCING THE SAME

Title (de)

SCHICHTSTRUKTUREN UND VERFAHREN ZU DEREN HERSTELLUNG

Title (fr)

STRUCTURES EN COUCHES ET LEUR PROCEDE DE PRODUCTION

Publication

**EP 1523783 A2 20050420 (DE)**

Application

**EP 03720146 A 20030228**

Priority

- DE 0300734 W 20030228
- DE 10208679 A 20020228
- DE 10261794 A 20021223

Abstract (en)

[origin: WO03078492A2] The invention relates to the use of suitable dispersions for constructing a galvanic element layer by layer. Said layers can be porous or impervious.

IPC 1-7

**H01M 8/10**

IPC 8 full level

**B01D 67/00** (2006.01); **B01D 71/52** (2006.01); **B01D 71/68** (2006.01); **B01D 71/80** (2006.01); **B01D 71/82** (2006.01); **C08G 65/48** (2006.01); **C08G 75/23** (2006.01); **C08J 5/22** (2006.01); **H01M 8/02** (2006.01); **H01M 8/10** (2006.01)

CPC (source: EP US)

**B01D 67/0093** (2013.01 - EP US); **B01D 71/52** (2013.01 - EP); **B01D 71/522** (2022.08 - US); **B01D 71/68** (2013.01 - EP US); **B01D 71/80** (2013.01 - EP US); **B01D 71/82** (2013.01 - EP US); **C08G 65/48** (2013.01 - EP US); **C08G 75/23** (2013.01 - EP US); **C08J 5/2256** (2013.01 - EP US); **H01M 8/0289** (2013.01 - EP US); **H01M 8/1023** (2013.01 - EP US); **H01M 8/1048** (2013.01 - EP US); **H01M 8/1069** (2013.01 - EP US); **B01D 2323/30** (2013.01 - EP US); **C08G 2650/02** (2013.01 - EP US); **C08J 2381/06** (2013.01 - EP US); **H01M 2300/0082** (2013.01 - EP US); **H01M 2300/0091** (2013.01 - EP US); **Y02E 60/50** (2013.01 - EP US); **Y02P 70/50** (2015.11 - EP US)

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PT SE SI SK TR

DOCDB simple family (publication)

**WO 03078492 A2 20030925; WO 03078492 A3 20040930;** AU 2003223846 A1 20030929; AU 2003223846 A8 20030929;  
CN 100593259 C 20100303; CN 1659731 A 20050824; DE 10391005 D2 20050414; EP 1523783 A2 20050420; JP 2005523561 A 20050804;  
JP 2011181506 A 20110915; JP 2014075354 A 20140424; JP 2015179677 A 20151008; JP 5507490 B2 20140528; JP 5898167 B2 20160406;  
US 2008233271 A1 20080925; US 2011104367 A1 20110505

DOCDB simple family (application)

**DE 0300734 W 20030228;** AU 2003223846 A 20030228; CN 03809526 A 20030228; DE 10391005 T 20030228; EP 03720146 A 20030228;  
JP 2003576489 A 20030228; JP 2011088462 A 20110412; JP 2013255647 A 20131211; JP 2015100623 A 20150518;  
US 201113005418 A 20110112; US 93730607 A 20071108